



### Dual Enclosure

### Specifications

Mounting Style:	Chassis Mounting
Permissible Temp. With / Without load:	-20 deg C to +85 Deg. C
Permissible Temp. For Soldering:	270 Deg. C for 5 seconds max.
Panel Thickness(Max):	N.A.
Material:	Polyamide G.F.
Insulation Resistance:	100 M Ohms min.
H. V. Break Down:	2 KVAC For 1 Minute
Current Carrying Parts:	Brass, Nickel Plated .
Contact Resistance (Initial):	10 m Ohms max.

Contd..

## Specifications - Contd..

---

Cap Design:	Press-on type
App. Weight(Gm):	44.6
Fuse Link Size:	6.3 x 32 mm
Rated Current / Voltage:	10 Amps, 250V AC
Terminals:	Screw-in



### Indian Technological Products Private Limited

22-23, Type-B, Hartron Complex, Electronic City, Sector-18, Udyog Vihar, Gurgaon -122 016, Haryana (India)

Telephone: +91-124-4013646, 4013647 • Fax: +91-124-2398277

Email: [sales@itpindia.in](mailto:sales@itpindia.in) • [www.itpindia.com](http://www.itpindia.com) • CIN: U74899DL1986PTC023265